

PNP -100mA -50V Digital Transistors (Bias Resistor Built-in Transistors)

Parameter	Value
V <sub>CC</sub>	-50V
I <sub>C(MAX.)</sub>	-100mA
R <sub>1</sub>	10kΩ
$R_2$	10kΩ

### Features

- 1) Built-In Biasing Resistors,  $R_1 = R_2 = 10k\Omega$
- Built-in bias resistors enable the configuration of an inverter circuit without connecting external input resistors (see inner circuit).
- 3) Only the on/off conditions need to be set for operation, making the circuit design easy.
- 4) Complementary NPN Types: DTC114E series

### Outline

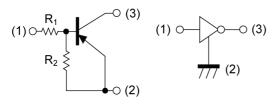
VMT3	EMT3F
(1)	(1)
DTA114EM	DTA114EEB
(SC-105AA)	(SC-89)
EMT3	UMT3F
DTA114EE	DTA114EUB
SOT-416(SC-75A)	(SC-85)
UMT3	SMT3 (3)
DTA114EUA	DTA114EKA
SOT-323(SC-70)	SOT-346(SC-59)

## Application

INVERTER, INTERFACE, DRIVER

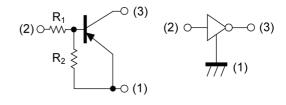
### •Inner circuit

DTA114EM/ DTA114EEB/ DTA114EUB



- (1) IN (BASE)
- (2) GND (+) (EMITTER)
- (3) OUT (COLLECTOR)

### DTA114EE/ DTA114EUA/ DTA114EKA



- (1) GND (+) (EMITTER)
- (2) IN (BASE)
- (3) OUT (COLLECTOR)

## Packaging specifications

Part No.	Package	Package size	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit.(pcs)	Marking
DTA114EM	VMT3	1212	T2L	180	8	8000	14
DTA114EEB	EMT3F	1616	TL	180	8	3000	14
DTA114EE	EMT3	1616	TL	180	8	3000	14
DTA114EUB	UMT3F	2021	TL	180	8	3000	14
DTA114EUA	UMT3	2021	T106	180	8	3000	14
DTA114EKA	SMT3	2928	T146	180	8	3000	14

# ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C)

Р	arameter	Symbol	Values	Unit
Supply voltage	V <sub>CC</sub>	-50	V	
Input voltage			-40 to 10	V
Output current			-50	mA
Collector current			-100	mA
	DTA114EM		150	
	DTA114EEB		150	
Dawar diagination	DTA114EE	P <sub>D</sub> *2	150	Da\\/
Power dissipation	DTA114EUB	P <sub>D</sub> -	200	mW
	DTA114EUA		200	
	DTA114EKA		200	
Junction temperature	T <sub>j</sub>	150	°C	
Range of storage tempera	ture	T <sub>stg</sub>	-55 to +150	°C

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Dougnoston	C: reals al	Conditions	Values			l lait
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
land to alkana	$V_{l(off)}$	$V_{CC} = -5V, I_{O} = -100\mu A$	-	-	-0.5	\/
Input voltage	V <sub>I(on)</sub>	$V_O = -0.3V$ , $I_O = -10$ mA	-3.0	-	-	V
Output voltage	V <sub>O(on)</sub>	$I_{O}/I_{I} = -10 \text{mA} / -0.5 \text{mA}$	-	-100	-300	mV
Input current	l <sub>l</sub>	V <sub>I</sub> = -5V	-	-	-880	μA
Output current	I <sub>O(off)</sub>	$V_{CC} = -50V, V_{I} = 0V$	-	-	-500	nA
DC current gain	G <sub>I</sub>	$V_{O} = -5V, I_{O} = -5mA$	30	-	-	-
Input resistance	R <sub>1</sub>	-	7	10	13	kΩ
Resistance ratio	R <sub>2</sub> /R <sub>1</sub>	-	0.8	1.0	1.2	-
Transition frequency	f <sub>T</sub> *1	V <sub>CE</sub> = -10V, I <sub>E</sub> = 5mA, f = 100MHz	-	250	-	MHz

<sup>\*1</sup> Characteristics of built-in transistor

<sup>\*2</sup> Each terminal mounted on a reference land

## ● Electrical characteristic curves (T<sub>a</sub> =25°C)

Fig.1 Input voltage vs. output current (ON characteristics)

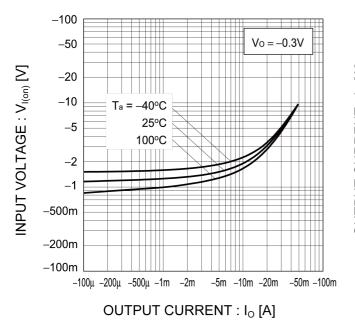


Fig.2 Output current vs. input voltage (OFF characteristics)

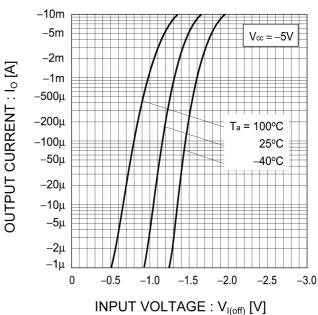


Fig.3 Output current vs. output voltage

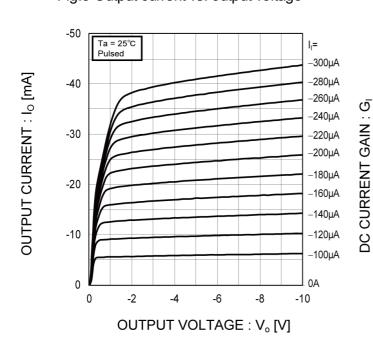
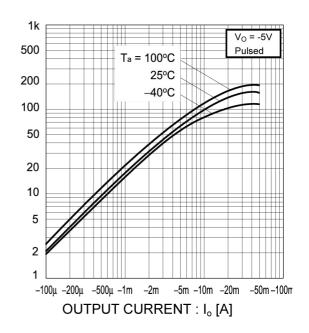


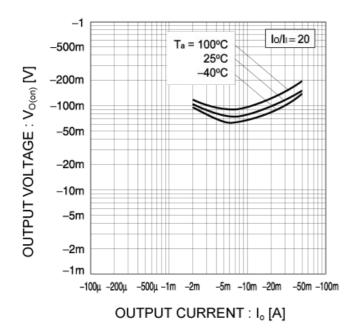
Fig.4 DC current gain vs. output current



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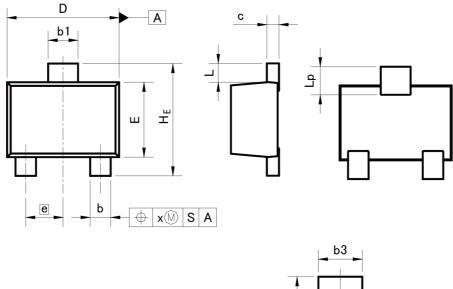
# ● Electrical characteristic curves (T<sub>a</sub> =25°C)

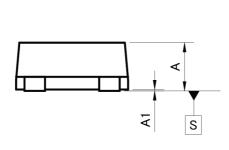
Fig.5 Output voltage vs. output current

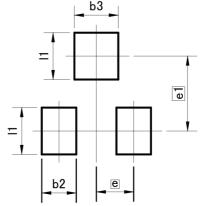




VMT3







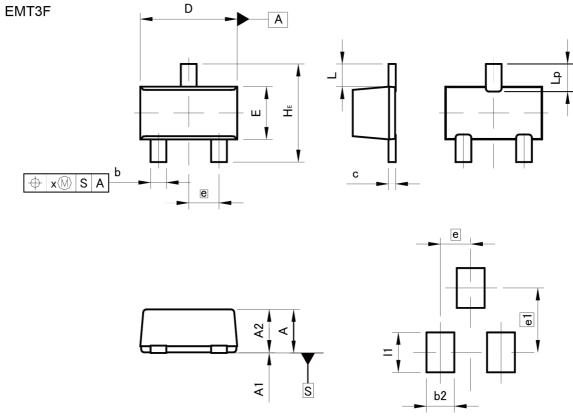
Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	0.45	0.55	0.018	0.022
A1	0.00	0.10	0.000	0.004
b	0.17	0.27	0.007	0.011
b1	0.27	0.37	0.011	0.015
С	0.08	0.18	0.003	0.007
D	1.10	1.30	0.043	0.051
Е	0.70	0.90	0.028	0.035
е	0.4	40	0.02	
HE	1.10	1.30	0.043	0.051
L	0.10	0.30	0.004	0.012
Lp	0.20	0.40	0.008	0.016
Х	_	0.10	_	0.004

DIM	MILIM	ETERS	INCHES	
DIM	MIN	MAX	MIN	MAX
b2	1	0.37	_	0.015
b3	ı	0.47	1	0.019
e1	0.80		0.0	31
11	_	0.50	-	0.020

Dimension in mm/inches





Pattern of terminal position areas [Not a recommended pattern of soldering pads]

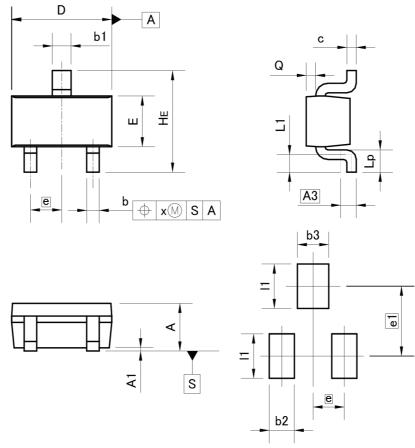
DIM	MILIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	0.65	0.85	0.026	0.033
A1	0.00	0.10	0.000	0.004
A2	0.60	0.80	0.024	0.031
b	0.21	0.36	0.008	0.014
С	0.08	0.18	0.003	0.007
D	1.50	1.70	0.059	0.067
E	0.76	0.96	0.030	0.038
е	0.	50	0.020	
HE	1.50	1.70	0.059	0.067
L	0.	37	0.015	
Lp	0.35	0.55	0.014	0.022
х	_	0.10	_	0.004

DIM	MILIMETERS		INCHES	
DIN	MIN	MAX	MIN	MAX
b2	ı	0.46	I	0.018
e1	ı	1.05	_	0.041
l1	ı	0.65	1	0.026

Dimension in mm/inches



EMT3



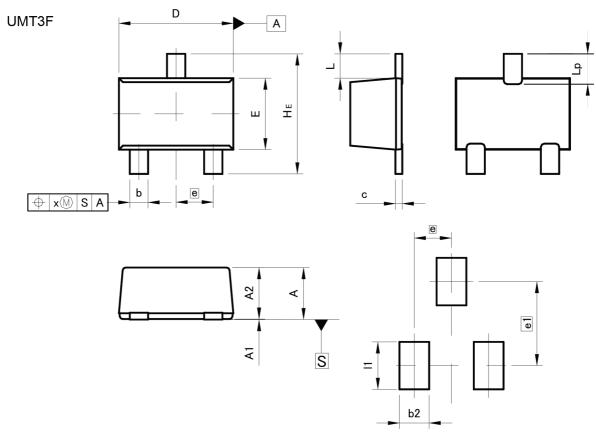
Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	0.60	0.80	0.024	0.031
A1	0.00	0.10	0.000	0.004
A3	0.:	25	0.0	10
b	0.15	0.30	0.006	0.012
b1	0.25	0.40	0.010	0.016
С	0.10	0.20	0.004	0.008
D	1.50	1.70	0.059	0.067
E	0.70	0.90	0.028	0.035
е	0.	50	0.0	20
HE	1.40	1.80	0.055	0.071
L1	0.10	-	0.004	-
Lp	0.15	-	0.006	_
Q	0.05	0.25	0.002	0.010
х	_	0.10	_	0.004

DIM	MILIMI	ETERS	INCHES	
DIM	MIN	MAX	MIN	MAX
b2	I	0.40	ı	0.016
b3	Ι	0.50	I	0.020
e1	1.10		0.0	43
11	_	0.70	_	0.028

Dimension in mm/inches





Pattern of terminal position areas [Not a recommended pattern of soldering pads]

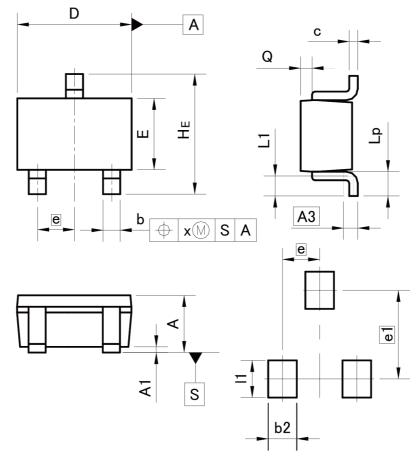
DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	0.85	1.05	0.033	0.041
A1	0.00	0.10	0.000	0.004
A2	0.80	1.00	0.031	0.039
b	0.27	0.42	0.011	0.017
С	0.08	0.18	0.003	0.007
D	1.90	2.10	0.075	0.083
E	1.15	1.35	0.045	0.053
е	0.0	65	0.026	
HE	2.00	2.20	0.079	0.087
L	0.4	43	0.0	17
Lp	0.43	0.63	0.017	0.025
х	_	0.10	_	0.004

	DIM	MILIMETERS		INCHES	
		MIN	MAX	MIN	MAX
	b2	ı	0.52	I	0.020
	e1	1.47		0.058	
	l1	- 0.83		I	0.033

Dimension in mm/inches



UMT3



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

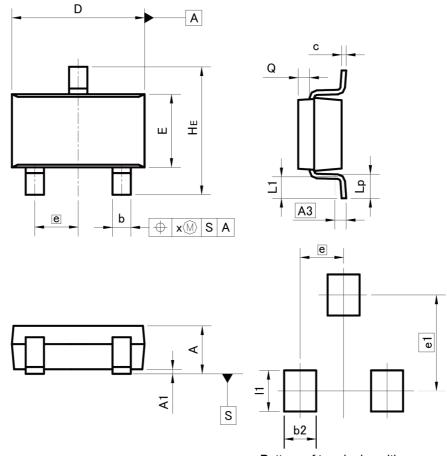
DIM	MILIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	0.80	1.00	0.031	0.039
A1	0.00	0.10	0.000	0.004
A3	3 0.25		0.010	
b	0.15	0.30	0.006	0.012
С	0.10	0.20	0.004	0.008
D	1.90	2.10	0.075	0.083
E	1.15	1.35	0.045	0.053
е	0.65		0.026	
HE	2.00	2.20	0.079	0.087
L1	0.20	0.50	0.008	0.020
Lp	0.25	0.55	0.010	0.022
Q	0.10	0.30	0.004	0.012
х	_	0.10	1	0.004

DIM	MILIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
b2	_	0.50	_	0.020
e1	1.55		0.061	
11	- 0.65		_	0.026

Dimension in mm/inches



SMT3



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	1.00	1.30	0.039	0.051
A1	0.00	0.10	0.000	0.004
A3	0.25		0.010	
b	0.35	0.50	0.014	0.020
С	0.09	0.25	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
е	0.95		0.037	
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.20	0.30	0.008	0.012
х	_	0.10	_	0.004
у	_	0.10	_	0.004

DIM	MILIMETERS		INCHES		
DIIVI	MIN	MAX	MIN	MAX	
b2	-	0.60	-	0.024	
e1	2.	2.10		0.083	
l1	-	0.90	ı	0.035	

Dimension in mm/inches



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1. If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), aircraft/spacecraft, nuclear power controllers, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

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Ì	JÁPAN	USA	EU	CHINA
Γ	CLASSⅢ	ОГАСОШ	CLASS II b	CI VCCIII
Γ	CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

### **Precaution for Mounting / Circuit board design**

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

#### **Precautions Regarding Application Examples and External Circuits**

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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